



AO4441

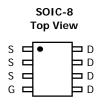
P-Channel Enhancement Mode Field Effect Transistor

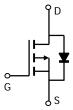
General Description

The AO4441 uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, and ultra-low low gate charge. This device is suitable for use as a load switch or in PWM applications. Standard Product AO4441 is Pb-free (meets ROHS & Sony 259 specifications). AO4441L is a Green Product ordering option. AO4441 and AO4441L are electrically identical.

Features

$$\begin{split} &V_{DS}\left(V\right) = -60V \\ &I_{D} = -4 \text{ A } \left(V_{GS} = -10V\right) \\ &R_{DS(ON)} < 100 \text{m}\Omega \left(V_{GS} = -10V\right) \\ &R_{DS(ON)} < 130 \text{m}\Omega \left(V_{GS} = -4.5V\right) \end{split}$$





Absolute Maximum Ratings T _A =25°C unless otherwise noted								
Parameter		Symbol	Maximum	Units				
Drain-Source Voltage		V_{DS}	-60	V				
Gate-Source Voltage		V_{GS}	±20	V				
Continuous Drain	T _A =25°C		-4					
Current ^A	T _A =70°C	I _D	-3.1	A				
Pulsed Drain Current ^B		I _{DM}	-20	7				
	T _A =25°C	В	3.1	W				
Power Dissipation A	T _A =70°C	$-P_D$	2	7 vv				
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 150	°C				

Thermal Characteristics									
Parameter	Symbol	Тур	Max	Units					
Maximum Junction-to-Ambient A	t ≤ 10s	В	24	40	°C/W				
Maximum Junction-to-Ambient A	Steady-State	dy-State $R_{\theta JA}$		75	°C/W				
Maximum Junction-to-Lead ^C	Steady-State	$R_{\theta JL}$	21	30	°C/W				

P-Channel Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter Conditions		Min	Тур	Max	Units				
STATIC PARAMETERS										
BV _{DSS}	Drain-Source Breakdown Voltage	I_D =-250 μ A, V_{GS} =0V	-60			V				
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-48V, V _{GS} =0V			-1 -5	μΑ				
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} =±20V			±100	nA				
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS} I_{D}=-250\mu A$	-1	-2.1	-3	V				
$I_{D(ON)}$	On state drain current	V _{GS} =-10V, V _{DS} =-5V	-20			Α				
	Static Drain-Source On-Resistance	V _{GS} =-10V, I _D =-4A		80	100	m()				
		T _J =125°C		130		mΩ				
		V _{GS} =-4.5V, I _D =-3A		102	130	mΩ				
g _{FS}	Forward Transconductance	V_{DS} =-5V, I_D =-4A		10		S				
V_{SD}	Diode Forward Voltage	I _S =-1A,V _{GS} =0V		-0.77	-1	V				
I _S	Maximum Body-Diode Continuous Current				-4	Α				
DYNAMIC	DYNAMIC PARAMETERS									
C _{iss}	Input Capacitance			930	1120	pF				
C _{oss}	Output Capacitance	V_{GS} =0V, V_{DS} =-30V, f=1MHz		85		pF				
C _{rss}	Reverse Transfer Capacitance			35		pF				
R_g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz		7.2	9	Ω				
SWITCHI	NG PARAMETERS									
Q _g (10V)	Total Gate Charge (10V)			16	20	nC				
Q _g (4.5V)	Total Gate Charge (4.5V)	V _{GS} =-10V, V _{DS} =-30V, I _D =-4A		8	10	nC				
Q_{gs}	Gate Source Charge	V _{GS} 10V, V _{DS} 50V, I _D 4A		2.5		nC				
Q_{gd}	Gate Drain Charge			3.2		nC				
$t_{D(on)}$	Turn-On DelayTime			8		ns				
t _r	Turn-On Rise Time	V_{GS} =-10V, V_{DS} =-30V, R_L =7.5 Ω ,		3.8		ns				
$t_{D(off)}$	Turn-Off DelayTime	R_{GEN} =3 Ω		31.5		ns				
t_f	Turn-Off Fall Time			7.5		ns				
t _{rr}	Body Diode Reverse Recovery Time	I _F =-4A, dI/dt=100A/μs		27	35	ns				
Q_{rr}	Body Diode Reverse Recovery Charge I _F =-4A, dI/dt=100A/μs			32		nC				

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t≤ 10s thermal resistance rating.

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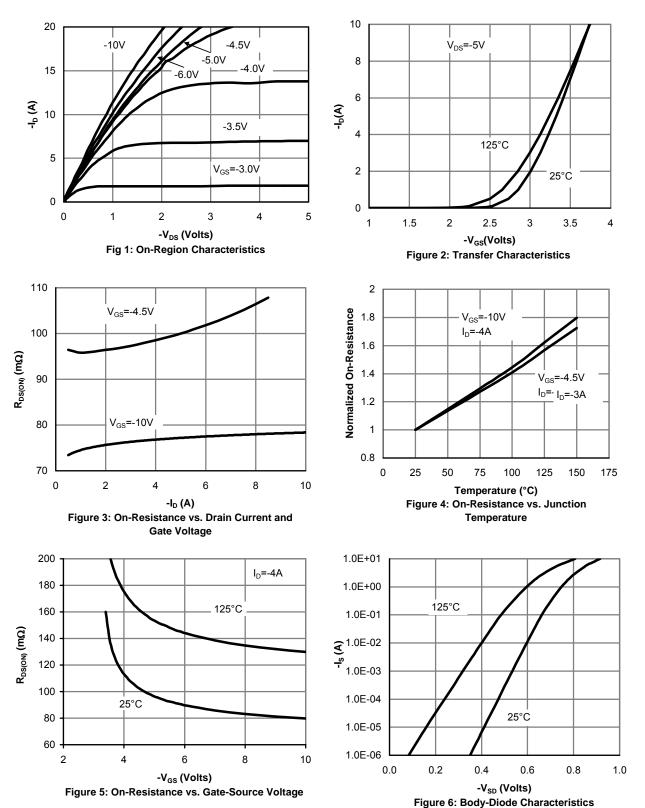
B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6,12,14 are obtained using $80\,\mu s$ pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS: P-CHANNEL



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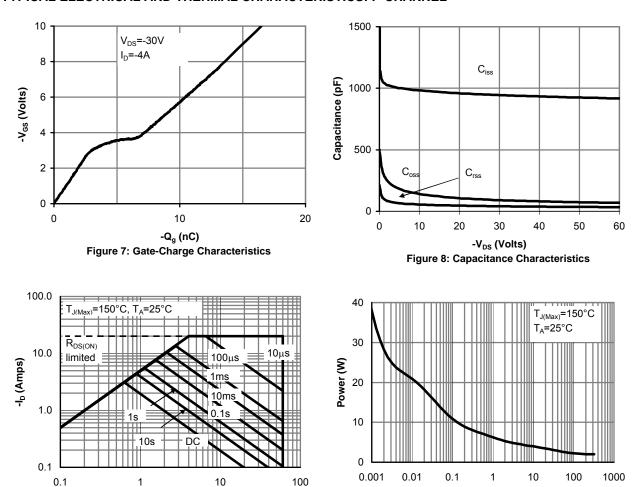


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

-V_{DS} (Volts)

Pulse Width (s)
Figure 10: Single Pulse Power Rating Junction-toAmbient (Note E)

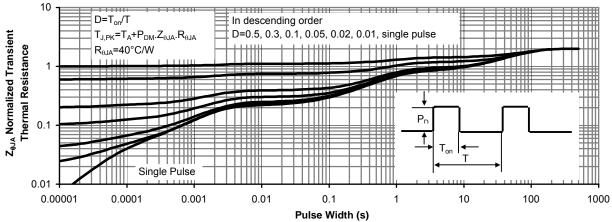


Figure 11: Normalized Maximum Transient Thermal Impedance